

# **Product Change Notification - KSRA-24DTJN091**

Date:

07 Nov 2019

**Product Category:** 

Voice Audio

**Affected CPNs:** 



### **Notification subject:**

CCB 3996, 3996.001 and 3996.002 Initial Notice: Qualification of MMT as a new assembly site for selected MSCC MT898XXX, MT90XXXX, MT912XXX and ZL500XXX device families available in 28L (11.5x11.5x4.4mm), 44L PLCC (16.6x16.6x4.4mm) and 68L PLCC (24.2x24.2x4.4 mm) packages using palladium coated copper with gold flash (CuPdAu) bond wire

#### **Notification text:**

#### **PCN Status:**

Initial notification

### **PCN Type:**

Manufacturing Change

### **Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

## **Description of Change:**

Qualification of MMT as a new assembly site for selected MSCC MT898XXX, MT907XXX, MT908XXX, MT912XXX and ZL500XXX device families available in 28L (11.5x11.5x4.4mm), 44L PLCC (16.6x16.6x4.4mm) and 68L PLCC (24.2x24.2x4.4 mm) packages using palladium coated copper with gold flash (CuPdAu) bond wire

#### **Pre Change:**

Assembled at ASEM assembly site copper (Cu) bond wire, YIZ8143 die attach and CEL 9240HF10AK-G1 molding compound material

# **Post Change:**

Assembled at MMT assembly site using palladium coated copper with gold flash (CuPdAu) bond wire 3280 die attach and G600V molding compound material

**Pre and Post Change Summary:** 

	Pre Change	Post Change				
Assembly Site	ASE Group -Malaysia /	Microchip Technology				
	ASEM	Thailand (Branch) / MMT				
Wire material	Cu wire	CuPdAu Wire				
Die attach material	YIZ8143	3280				
Molding compound material	CEL 9240HF10AK-G1	G600V				
Lead frame material	A194	A194				

#### **Impacts to Data Sheet:**

None

### **Change Impact:**

None

#### **Reason for Change:**

To improve manufacturability and on-time delivery by qualifying MMT as new assembly site

## **Change Implementation Status:**

In Progress



### **Estimated Qualification Completion Date:**

January 2020

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

### **Time Table Summary:**

	November 2019					January 2020					
Workweek	44	45	46	47	48	>	01	02	03	04	05
Initial PCN Issue Date		X									
Qual Report Availability								X			
Final PCN Issue Date								X			

#### Method to Identify Change:

Traceability code

#### **Qualification Plan:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

#### **Revision History:**

November 07, 2019: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## Attachment(s):

PCN\_KSRA-24DTJN091\_Qual\_Plan.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

#### **Terms and Conditions:**

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN home page</u> select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile, including opt out,</u> please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

MT8985AP1

MT8986AP1

MT8986APR1

MT9074AP1

MT9074APR1

MT9075BP1

MT90812AP1

MT9122AP1

MT9123AP1

MT9123APR1

ZL50002AP1

Date: Thursday, November 07, 2019